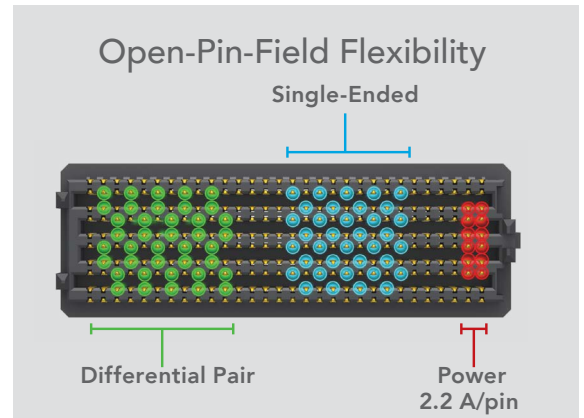




LOW PROFILE OPEN-PIN-FIELD ARRAYS

LP ARRAY™ HIGH-SPEED/HIGH-DENSITY SYSTEMS

- Low profile stack heights: 4 mm, 4.5 mm and 5 mm
- .050" (1.27 mm) pitch for maximum grounding and routing flexibility
- Up to 50 pins per row
- 4, 6 or 8 row configurations
- Dual beam contact system
- Solder crimped termination for ease of processing
- Board stacking standoffs available to assist unmating and reduce risk for component damage on boards
- Press-in or threaded standoffs available to assist with unmating (JSO)



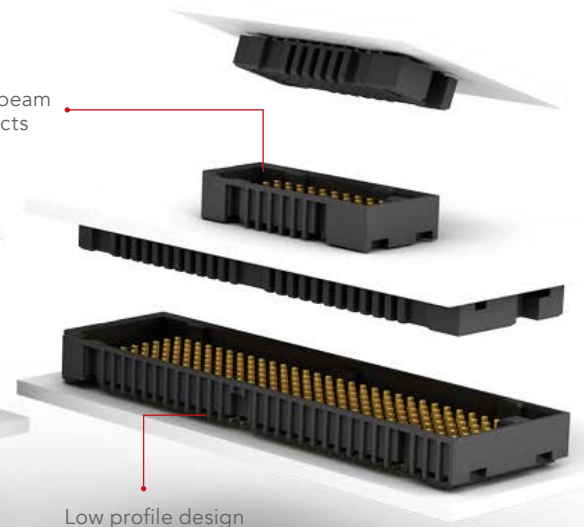
LP ARRAY™

PAM4
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G b p s



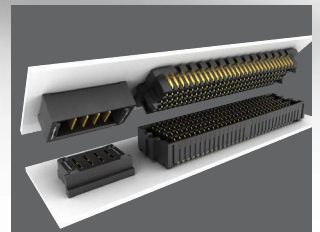
Press-in or threaded stand offs

Dual beam contacts



Low profile design

LP Array™ is compatible with UMPT/UMPS for flexible two-piece power/signal solutions.



System

- LPAM – .050" Pitch Array Terminal
- LPAF – .050" Pitch Array Socket
- JSO – Jack Screw Precision Board Stacking Standoff

For more High-Speed/High-Density Solutions, please visit samtec.com/arrays